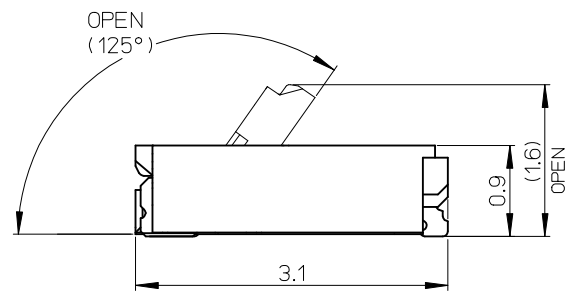


注記
NOTES:

1.材質
MATERIAL
ハウジング:LCP(液晶ポリマー)、ガラス充填、UL94V-0
HOUSING:LCP(LIQUID CRYSTAL POLYMER),
GLASS FILLED,UL94V-0
アクチュエータ:ナイロン、ガラス充填、UL94V-0
ACTUATOR:NYLON(POLYAMIDE),
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.15)
TERMINAL:COPPER ALLOY(t=0.15)
金具:銅合金(t=0.15)
NAIL:COPPER ALLOY(t=0.15)

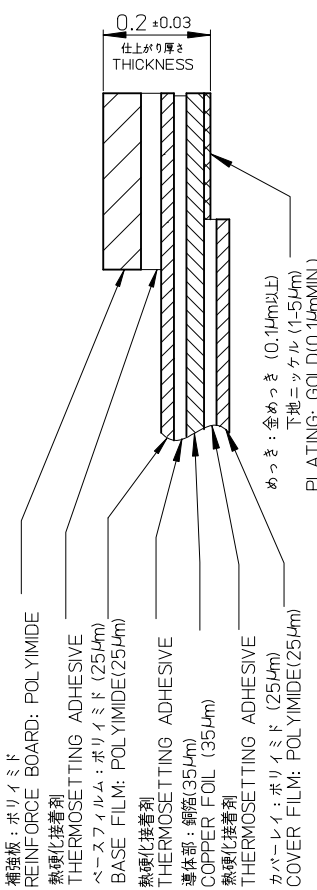
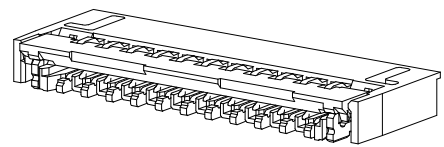
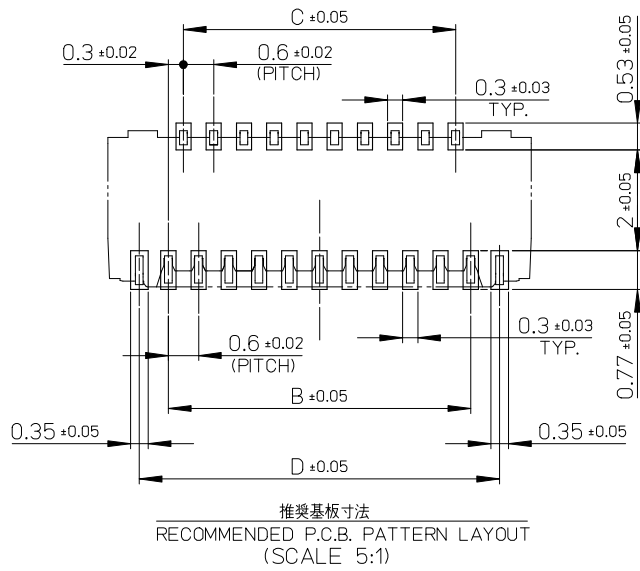
2.めっき仕様
PLATING
ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
金具
NAIL
錫めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



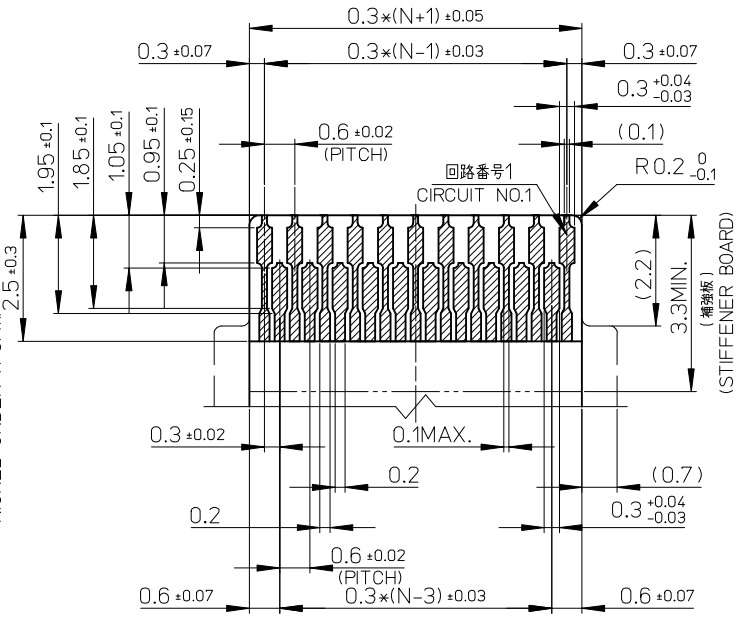
0.1	16.15	14.4	15	17.4	501628-5181	51
0.089	14.35	12.6	13.2	15.6	501628-4581	45
0.078	12.55	10.8	11.4	13.8	501628-3981	39
0.075	11.95	10.2	10.8	13.2	501628-3781	37
0.071	11.35	9.6	10.2	12.6	501628-3581	35
0.067	10.75	9.0	9.6	12.0	501628-3381	33
0.064	10.15	8.4	9	11.4	501628-3181	31
0.056	8.95	7.2	7.8	10.2	501628-2781	27
0.046	7.15	5.4	6	8.4	501628-2181	21
0.028	4.15	2.4	3	5.4	501628-1181	11
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER No.	極数 CIRCUITS

CONNECTOR SERIES No. 501628-***12

REVISED EC NO: J2010-0068 DRWN:KUSATO 2009/07/30 CHKD:SHIMOYAMA 2009/07/31 APPR:KMORIKAWA 2009/07/31 REV K	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMOYAMA	DATE 2005/08/08	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER		
	10 OVER 30 UNDER	±0.25	CHECKED BY HHIRATA	DATE 2005/08/08	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2005/08/08	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501628-002	SHEET NO. 1 OF 2
	ANGULAR ±1 °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						



FPC構成推奨仕様
STRUCTURE OF FPC



適用する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

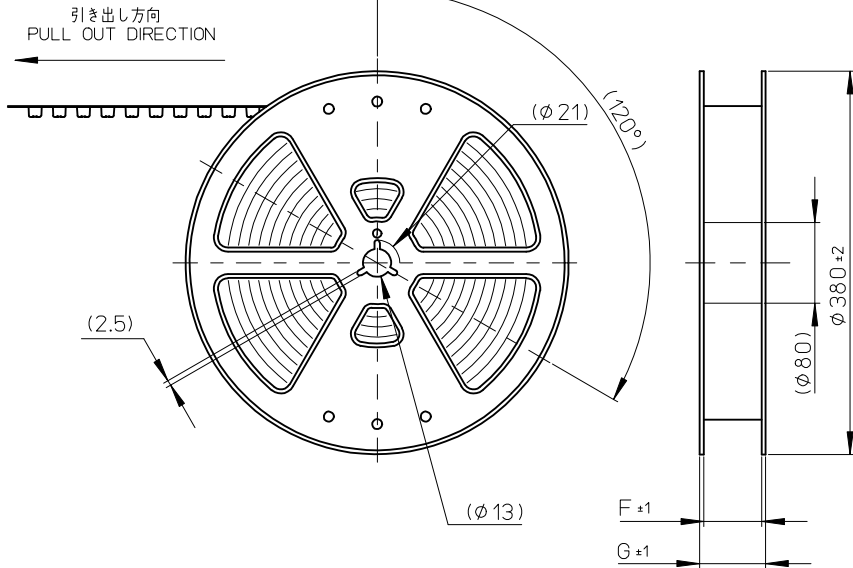
FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

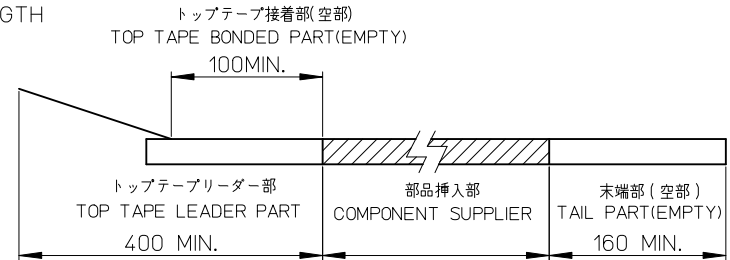
REVISED EC NO: J2010-0068 DRWN: KUSATO 2009/07/30 CHKD: HSHIMOYAMA 2009/07/31 APPR: KMORIKAWA 2009/07/31 K	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY HSHIMOYAMA	DATE 2005/08/08	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER			
		10 OVER 30 UNDER	± ---	CHECKED BY HHIRATA	DATE 2005/08/08	MOLEX INCORPORATED			
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/08	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501628-002	SHEET NO. 2 OF 2
ANGULAR ± --- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

注記)
NOTES

1. 製品番号501628-***12の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-***12 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH

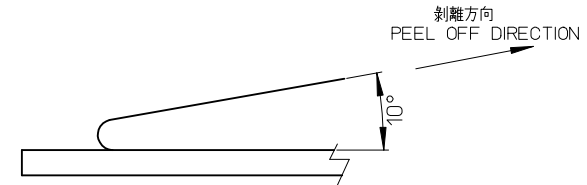


引き出し方向
PULL OUT DIRECTION



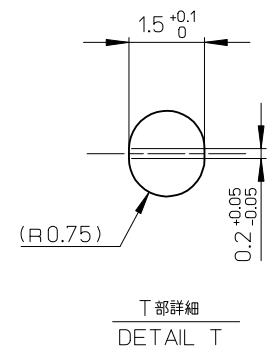
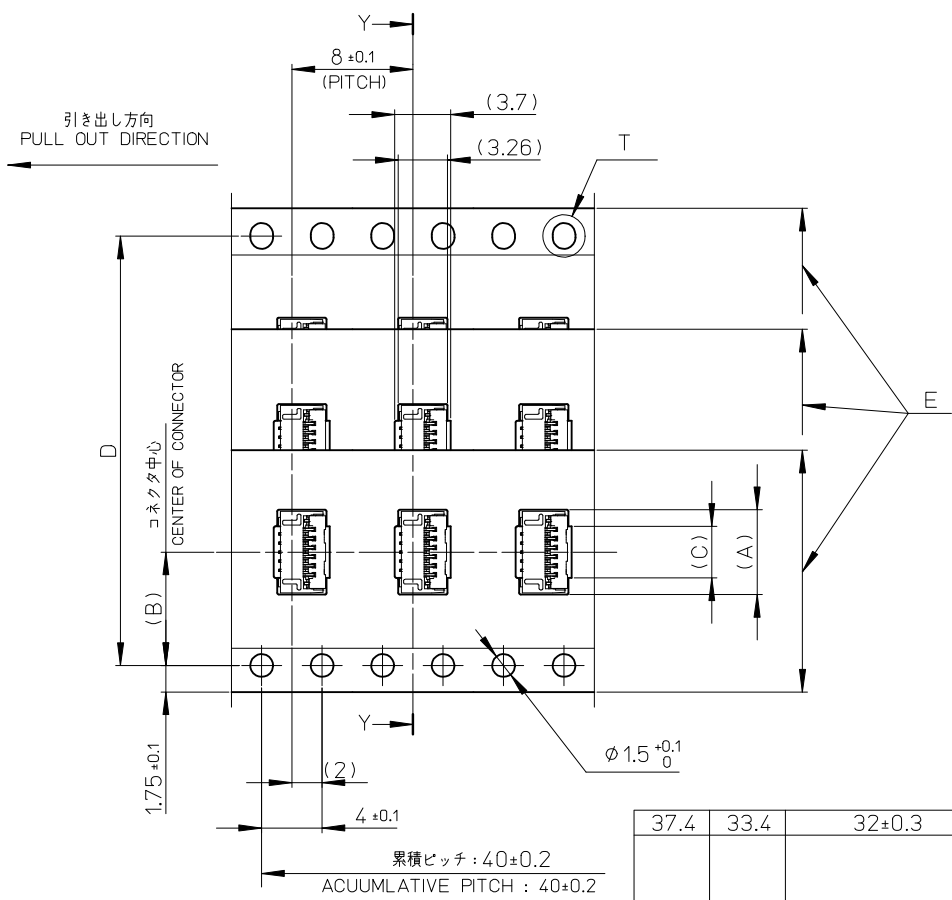
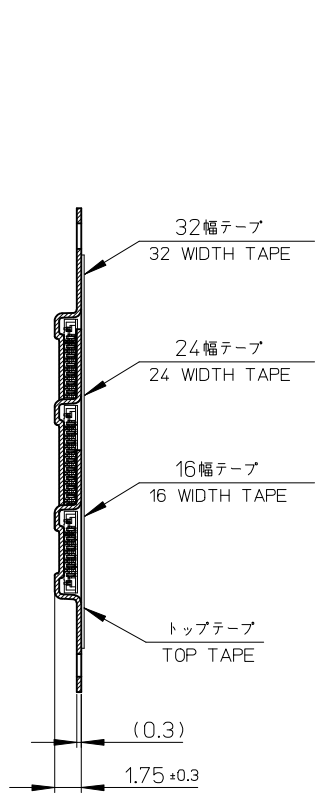
4. トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.)

引き出し方向
PULL OUT DIRECTION



5. 材料
MATERIAL
キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: PET, PE, PEF
TOP TAPE : PET, PE, PEF
リール: ポリスチレン
REEL: POLYSTYRENE
6. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2010-0068 DRWN: KUSATO 2009/07/30 CHKD: HSHIMOYAMA 2009/07/31 APP: KMORIKAWA 2009/07/31	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HSHIMOYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628-***12) TAPING PACKAGE NICKEL BARRIER				
		10 OVER 30 UNDER	± ---	CHECKED BY HHIRATA	DATE 2005/08/22	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	DOCUMENT NO. SD-501628-004				
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2				
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



37.4	33.4	32±0.3	28.4	15.4	14.2	17.6	501628-5181	51	
29.4	25.4	24±0.3	---	13.6	11.5	15.8	501628-4581	45	
				11.8		14	501628-3981	39	
				11.2		13.4	501628-3781	37	
				10.6		12.8	501628-3581	35	
				10.0		12.2	501628-2181	33	
				9.4		11.6	501628-2181	31	
21.4	17.4	16±0.3	---	8.2	7.5	10.4	501628-2181	27	
				6.4		8.6	501628-2181	21	
				3.4		5.6	501628-1181	11	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH		D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2010-0068 DRWKUSATO 2009/07/30 CHKD:HSHIROYAMA 2009/07/31 APPR:KMORIKAWA 2009/07/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY HSHIROYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**12) TAPING PACKAGE NICKEL BARRIER			
	10 OVER 30 UNDER	± ---	CHECKED BY HIRATA	DATE 2005/08/22	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501628-004	SHEET NO. 2 OF 2
ANGULAR	± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				